
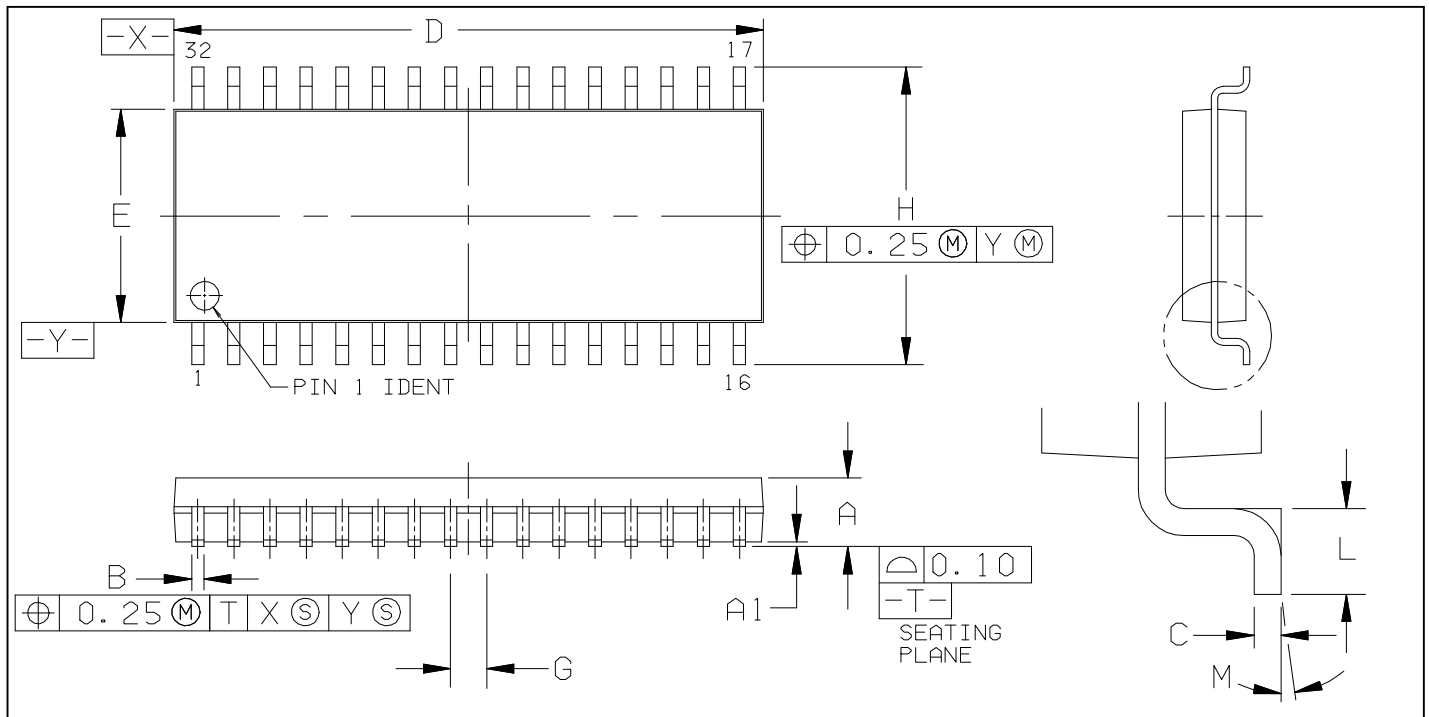


ON Semiconductor 	MECHANICAL OUTLINES DICTIONARY	98AON03783D	
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DO NOT SCALE THIS DWG	ALL APPROVAL SIGNATURES ON FILE IN DOCUMENT CENTRAL	ISSUE 0	SHEET 1 OF 2



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.29	2.54		
A1	0.10	0.25		
B	0.36	0.51		
C	0.15	0.32		
D	20.57	20.88		
E	7.42	7.60		
G	1.27 BSC			
H	10.29	10.64		
L	0.53	1.04		
M	0°	8°		

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MM
3. DIMENSIONS "D" AND "E" DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION "B" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF "B" DIMENSION AT MAXIMUM MATERIAL CONDITION.

CASE NO.	751P-01
STATUS	ON SEMICONDUCTOR STANDARD
NEW STD	
USED ON	SOIC WIDE BODY, 32 LEAD



ISSUE	REVISION	COORD/ DATE
0	RELEASED FOR PRODUCTION. REQ. BY S. MOHAMMED	FB 02 NOV 00